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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	27
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21335cnfp-30

1.1.2   Specifications

Tables 1.1 and 1.2 outline the Specifications for R8C/33C Group.

Table 1.1   Specifications for R8C/33C Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 　　50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V) 　　200 ns (f(XIN) = 5 MHz, VCC = 1.8 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, Data flash	Refer to **Table 1.3 Product List for R8C/33C Group**.
Power Supply Voltage Detection	Voltage detection circuit	• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	• Input-only: 1 pin • CMOS I/O ports: 27, selectable pull-up resistor • High current drive ports: 27
Clock	Clock generation circuits	4 circuits: XIN clock oscillation circuit, 　　　　　　XCIN clock oscillation circuit (32 kHz), 　　　　　　High-speed on-chip oscillator (with frequency adjustment function), 　　　　　　Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: 　Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		• Number of interrupt vectors: 69 • External Interrupt: 7 (INT × 3, Key input × 4) • Priority levels: 7 levels
Watchdog Timer		• 14 bits × 1 (with prescaler) • Reset start selectable • Low-speed on-chip oscillator for watchdog timer selectable
DTC (Data Transfer Controller)		• 1 channel • Activation sources: 23 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timer RA	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits × 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RE	8 bits × 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode

Table 1.2   Specifications for R8C/33C Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1	Clock synchronous serial I/O/UART × 2 channel
	UART2	Clock synchronous serial I/O/UART, I^2C mode (I^2C-bus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 (shared with I^2C-bus)
I^2C bus		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution × 2 circuits
Comparator B		2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • Background operation (BGO) function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption		Typ. 6.5 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) [1]
Package		32-pin LQFP Package code: PLQP0032GB-A (previous code: 32P6U-A)

Note:
    1. Specify the D version if D version functions are to be used.

Table 1.4   Pin Name Information by Pin Number

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I²C bus	A/D Converter, D/A Converter, Comparator B
1		P4_2						VREF
2	MODE							
3	$\overline{\text{RESET}}$							
4	XOUT(/XCOUT)	P4_7						
5	VSS/AVSS							
6	XIN(/XCIN)	P4_6						
7	VCC/AVCC							
8		P3_7		TRAO	(RXD2/SCL2/ TXD2/SDA2)	SSO	SDA	
9		P3_5		(TRCIOD)	(CLK2)	SSCK	SCL	
10		P3_4		(TRCIOC)	(RXD2/SCL2/ TXD2/SDA2)	SSI		IVREF3
11		P3_3	$\overline{\text{INT3}}$	(TRCCLK)	($\overline{\text{CTS2}}$/$\overline{\text{RTS2}}$)	$\overline{\text{SCS}}$		IVCMP3
12		P2_2		(TRCIOD)				
13		P2_1		(TRCIOC)				
14		P2_0	($\overline{\text{INT1}}$)	(TRCIOB)				
15		P3_1		(TRBO)				
16		P4_5	$\overline{\text{INT0}}$		(RXD2/SCL2)			$\overline{\text{ADTRG}}$
17		P1_7	$\overline{\text{INT1}}$	(TRAIO)				IVCMP1
18		P1_6			(CLK0)			IVREF1
19		P1_5	($\overline{\text{INT1}}$)	(TRAIO)	(RXD0)			
20		P1_4		(TRCCLK)	(TXD0)			
21		P1_3	$\overline{\text{KI3}}$	TRBO (/TRCIOC)				AN11
22		P1_2	$\overline{\text{KI2}}$	(TRCIOB)				AN10
23		P1_1	$\overline{\text{KI1}}$	(TRCIOA/ TRCTRG)				AN9
24		P1_0	$\overline{\text{KI0}}$	(TRCIOD)				AN8
25		P0_7		(TRCIOC)				AN0/DA1
26		P0_6		(TRCIOD)				AN1/DA0
27		P0_5		(TRCIOB)				AN2
28		P0_4		TREO (/TRCIOB)				AN3
29		P0_3		(TRCIOB)	(CLK1)			AN4
30		P0_2		(TRCIOA/ TRCTRG)	(RXD1)			AN5
31		P0_1		(TRCIOA/ TRCTRG)	(TXD1)			AN6
32		P0_0		(TRCIOA/ TRCTRG)				AN7

Note:
1. Can be assigned to the pin in parentheses by a program.

1.5   Pin Functions

Tables 1.5 and 1.6 list Pin Functions.

Table 1.5   Pin Functions (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins [1]. To use an external clock, input it to the XOUT pin and leave the XIN pin open.
XIN clock output	XOUT	I/O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between the XCIN and XCOUT pins [1]. To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$, $\overline{\text{INT1}}$, $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ is timer RB, and RC input pin.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RE	TREO	O	Divided clock output pin
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^{2}C mode clock I/O pin
	SDA2	I/O	I^{2}C mode data I/O pin
I^{2}C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin

I: Input   O: Output   I/O: Input and output
Note:
  1. Refer to the oscillator manufacturer for oscillation characteristics.

Table 1.6   Pin Functions (2)

Item	Pin Name	I/O Type	Description
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter and D/A converter
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
	$\overline{\text{ADTRG}}$	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_2, P3_1, P3_3 to P3_5, P3_7, P4_5 to P4_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. All ports can be used as LED drive ports.
Input port	P4_2	I	Input-only port

I: Input   O: Output   I/O: Input and output

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

2.8.7　Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8　Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9　Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10　Reserved Bit

If necessary, set to 0. When read, the content is undefined.

Table 4.2 SFR Information (2) [1]

Address	Register	Symbol	After Reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h			
0049h			
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register / IIC bus Interrupt Control Register [2]	SSUIC / IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h			
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h	Voltage Monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0073h	Voltage Monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

Notes:
1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IICSEL bit in the SSUIICSR register.

Table 4.3   SFR Information (3) [1]

Address	Register	Symbol	After Reset
0080h	DTC Activation Control Register	DTCTL	00h
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h	DTC Activation Enable Register 0	DTCEN0	00h
0089h	DTC Activation Enable Register 1	DTCEN1	00h
008Ah	DTC Activation Enable Register 2	DTCEN2	00h
008Bh	DTC Activation Enable Register 3	DTCEN3	00h
008Ch			
008Dh	DTC Activation Enable Register 5	DTCEN5	00h
008Eh	DTC Activation Enable Register 6	DTCEN6	00h
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh			XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined
Note:
   1. The blank areas are reserved and cannot be accessed by users.

Table 4.6   SFR Information (6) [1]

Address	Register	Symbol	After Reset
0140h			
0141h			
0142h			
0143h			
0144h			
0145h			
0146h			
0147h			
0148h			
0149h			
014Ah			
014Bh			
014Ch			
014Dh			
014Eh			
014Fh			
0150h			
0151h			
0152h			
0153h			
0154h			
0155h			
0156h			
0157h			
0158h			
0159h			
015Ah			
015Bh			
015Ch			
015Dh			
015Eh			
015Fh			
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined
Note:
1. The blank areas are reserved and cannot be accessed by users.

Table 4.7 **SFR Information (7)** [1]

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h			
0185h			
0186h			
0187h			
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUIICSR	00h
018Dh			
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	11111000b
0194h	SS Transmit Data Register L / IIC bus Transmit Data Register [2]	SSTDR / ICDRT	FFh
0195h	SS Transmit Data Register H [2]	SSTDRH	FFh
0196h	SS Receive Data Register L / IIC bus Receive Data Register [2]	SSRDR / ICDRR	FFh
0197h	SS Receive Data Register H [2]	SSRDRH	FFh
0198h	SS Control Register H / IIC bus Control Register 1 [2]	SSCRH / ICCR1	00h
0199h	SS Control Register L / IIC bus Control Register 2 [2]	SSCRL / ICCR2	01111101b
019Ah	SS Mode Register / IIC bus Mode Register [2]	SSMR / ICMR	00010000b / 00011000b
019Bh	SS Enable Register / IIC bus Interrupt Enable Register [2]	SSER / ICIER	00h
019Ch	SS Status Register / IIC bus Status Register [2]	SSSR / ICSR	00h / 0000X000b
019Dh	SS Mode Register 2 / Slave Address Register [2]	SSMR2 / SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined
Notes:
1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IICSEL bit in the SSUIICSR register.

5.   Electrical Characteristics

Table 5.1   Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		−0.3 to 6.5	V
V_I	Input voltage		−0.3 to V_{CC} + 0.3	V
V_O	Output voltage		−0.3 to V_{CC} + 0.3	V
P_d	Power dissipation	−40°C ≤ T_{opr} ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature		−20 to 85 (N version) / −40 to 85 (D version)	°C
T_{stg}	Storage temperature		−65 to 150	°C

Table 5.6   Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
−	Program/erase endurance [2]		1,000 [3]	−	−	times
−	Byte program time		−	80	500	μs
−	Block erase time		−	0.3	−	s
$t_{d(SR\text{-}SUS)}$	Time delay from suspend request until suspend		−	−	5+CPU clock × 3 cycles	ms
−	Interval from erase start/restart until following suspend request		0	−	−	μs
−	Time from suspend until erase restart		−	−	30+CPU clock × 1 cycle	μs
$t_{d(CMDRST\text{-}READY)}$	Time from when command is forcibly terminated until reading is enabled		−	−	30+CPU clock × 1 cycle	μs
−	Program, erase voltage		2.7	−	5.5	V
−	Read voltage		1.8	−	5.5	V
−	Program, erase temperature		0	−	60	°C
−	Data hold time [7]	Ambient temperature = 55°C	20	−	−	year

Notes:
1. V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.
2. Definition of programming/erasure endurance
    The programming and erasure endurance is defined on a per-block basis.
    If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
    However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.7   Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Symbol	Parameter	Conditions	Standard Min.	Standard Typ.	Standard Max.	Unit
−	Program/erase endurance [2]		10,000 [3]	−	−	times
−	Byte program time (program/erase endurance ≤ 1,000 times)		−	160	1,500	µs
−	Byte program time (program/erase endurance > 1,000 times)		−	300	1,500	µs
−	Block erase time (program/erase endurance ≤ 1,000 times)		−	0.2	1	s
−	Block erase time (program/erase endurance > 1,000 times)		−	0.3	1	s
$t_{d(SR\text{-}SUS)}$	Time delay from suspend request until suspend		−	−	5+CPU clock × 3 cycles	ms
−	Interval from erase start/restart until following suspend request		0	−	−	µs
−	Time from suspend until erase restart		−	−	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST\text{-}READY)}$	Time from when command is forcibly terminated until reading is enabled		−	−	30+CPU clock × 1 cycle	µs
−	Program, erase voltage		2.7	−	5.5	V
−	Read voltage		1.8	−	5.5	V
−	Program, erase temperature		−20 [7]	−	85	°C
−	Data hold time [8]	Ambient temperature = 55 °C	20	−	−	year

Notes:
1. V_{CC} = 2.7 to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.
2. Definition of programming/erasure endurance
    The programming and erasure endurance is defined on a per-block basis.
    If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
    However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. −40°C for D version.
8. The data hold time includes time that the power supply is off or the clock is not supplied.
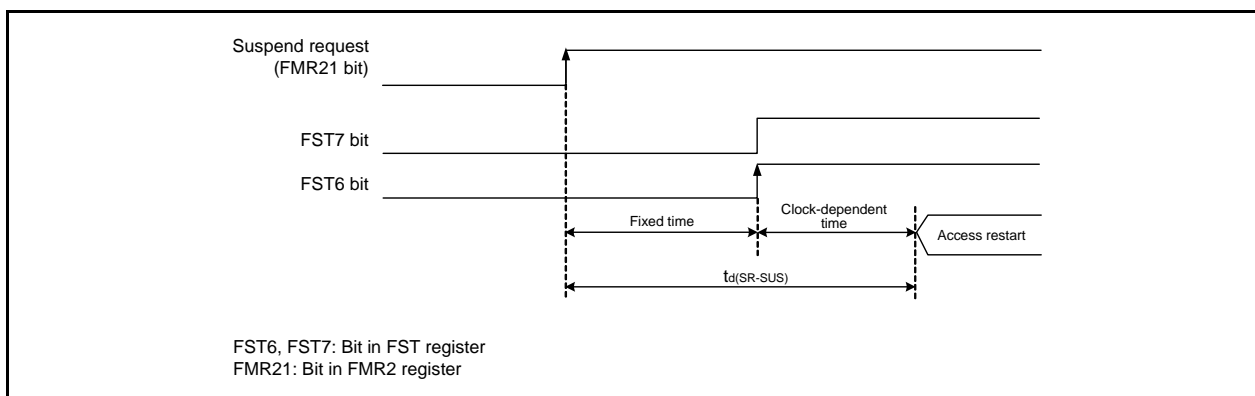

Figure 5.2   Time delay until Suspend

Table 5.8 Voltage Detection 0 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet0	Voltage detection level Vdet0_0 [2]		1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 [2]		2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 [2]		2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 [2]		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time [4]	At the falling of Vcc from 5 V to (Vdet0_0 − 0.1) V	−	6	150	μs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	−	1.5	−	μA
td(E-A)	Waiting time until voltage detection circuit operation starts [3]		−	−	100	μs

Notes:
1. The measurement condition is V_{CC} = 1.8 V to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version).
2. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
4. Time until the voltage monitor 0 reset is generated after the voltage passes Vdet0.

Table 5.9 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet1	Voltage detection level Vdet1_0 [2]	At the falling of Vcc	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 [2]	At the falling of Vcc	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 [2]	At the falling of Vcc	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 [2]	At the falling of Vcc	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 [2]	At the falling of Vcc	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 [2]	At the falling of Vcc	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 [2]	At the falling of Vcc	2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 [2]	At the falling of Vcc	3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 [2]	At the falling of Vcc	3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 [2]	At the falling of Vcc	3.30	3.55	3.85	V
	Voltage detection level Vdet1_A [2]	At the falling of Vcc	3.45	3.70	4.00	V
	Voltage detection level Vdet1_B [2]	At the falling of Vcc	3.60	3.85	4.15	V
	Voltage detection level Vdet1_C [2]	At the falling of Vcc	3.75	4.00	4.30	V
	Voltage detection level Vdet1_D [2]	At the falling of Vcc	3.90	4.15	4.45	V
	Voltage detection level Vdet1_E [2]	At the falling of Vcc	4.05	4.30	4.60	V
	Voltage detection level Vdet1_F [2]	At the falling of Vcc	4.20	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	−	0.07	−	V
		Vdet1_6 to Vdet1_F selected	−	0.10	−	V
—	Voltage detection 1 circuit response time [3]	At the falling of Vcc from 5 V to (Vdet1_0 − 0.1) V	−	60	150	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	−	1.7	−	μA
td(E-A)	Waiting time until voltage detection circuit operation starts [4]		−	−	100	μs

Notes:
1. The measurement condition is V_{CC} = 1.8 V to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version).
2. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
3. Time until the voltage monitor 1 interrupt request is generated after the voltage passes Vdet1.
4. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.10   Voltage Detection 2 Circuit Electrical Characteristics

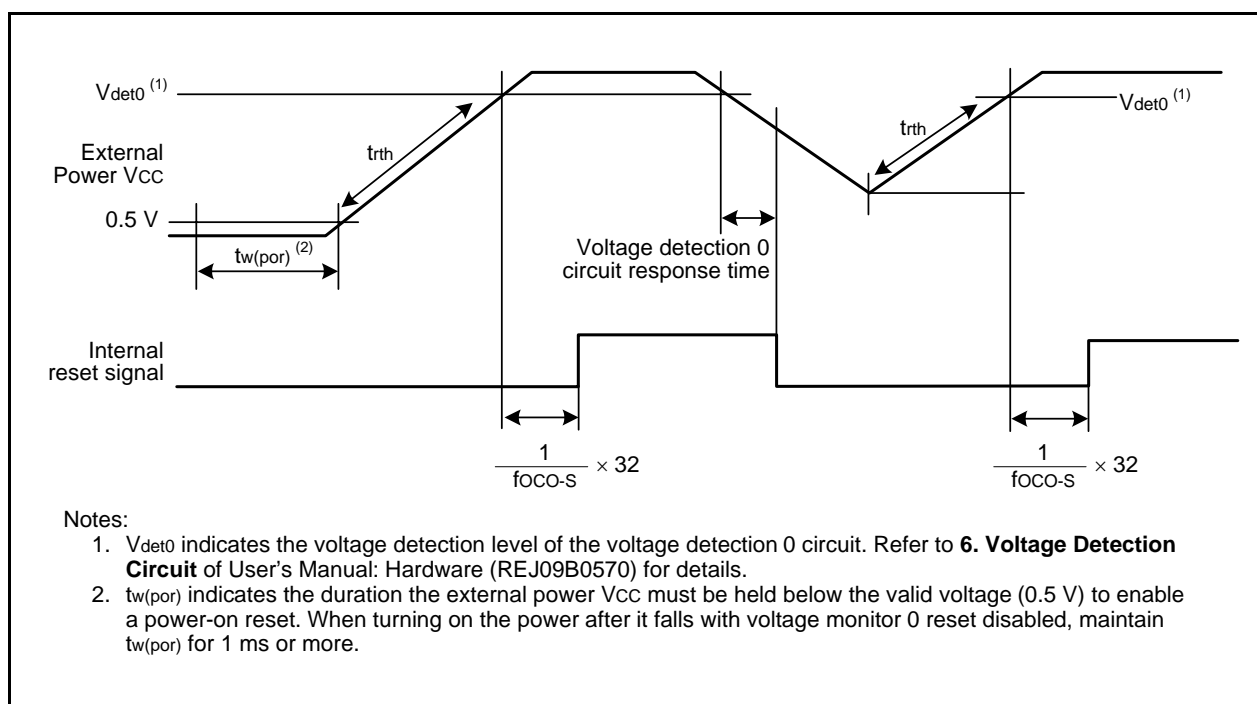| Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	At the falling of V_{CC}	3.70	4.00	4.30	V
–	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		–	0.10	–	V
–	Voltage detection 2 circuit response time [2]	At the falling of Vcc from 5 V to (Vdet2_0 − 0.1) V	–	20	150	μs
–	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	–	1.7	–	μA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts [3]		–	–	100	μs

Notes:
1. The measurement condition is VCC = 1.8 V to 5.5 V and Topr = −20 to 85°C (N version) / −40 to 85°C (D version).
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.11   Power-on Reset Circuit [2]

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power V_{CC} rise gradient	[1]	0	–	50,000	mV/msec

Notes:
1. The measurement condition is Topr = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.
2. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.

Notes:
1. Vdet0 indicates the voltage detection level of the voltage detection 0 circuit. Refer to **6. Voltage Detection Circuit** of User's Manual: Hardware (REJ09B0570) for details.
2. tw(por) indicates the duration the external power VCC must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain tw(por) for 1 ms or more.

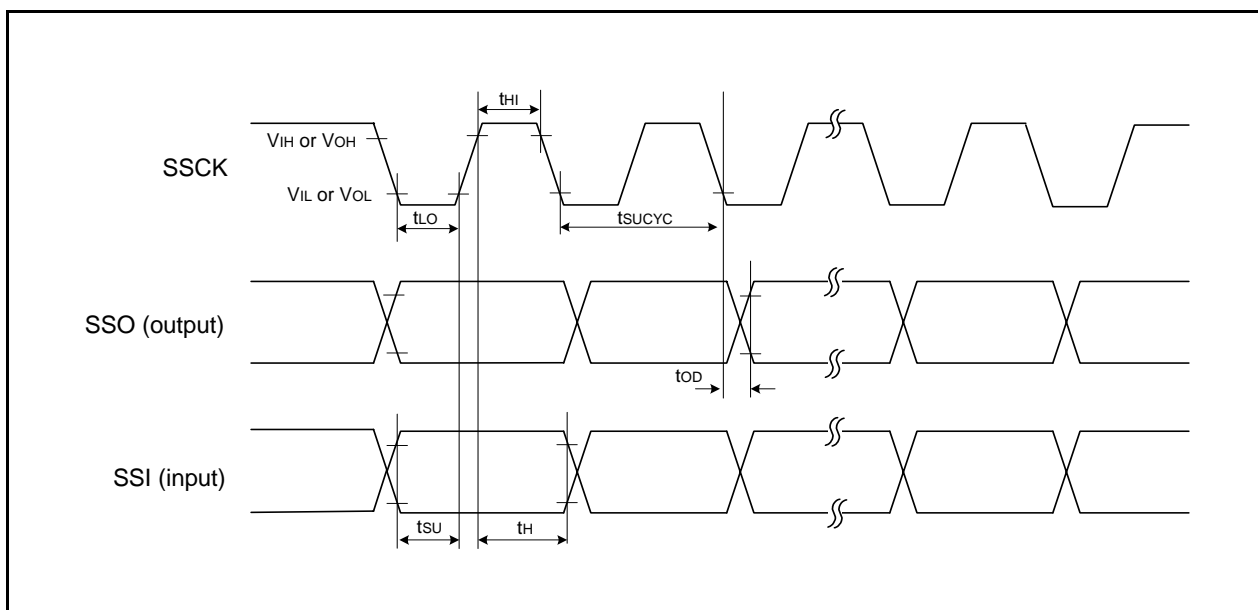**Figure 5.3   Power-on Reset Circuit Electrical Characteristics**

Figure 5.6   I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

**Table 5.17   Electrical Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V]**

| Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
VOH	Output "H" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOH = −20 mA	Vcc − 2.0	–	Vcc	V
			Drive capacity Low Vcc = 5 V	IOH = −5 mA	Vcc − 2.0	–	Vcc	V
		XOUT	Vcc = 5 V	IOH = −200 μA	1.0	–	Vcc	V
VOL	Output "L" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOL = 20 mA	–	–	2.0	V
			Drive capacity Low Vcc = 5 V	IOL = 5 mA	–	–	2.0	V
		XOUT	Vcc = 5 V	IOL = 200 μA	–	–	0.5	V
VT+-VT-	Hysteresis	INT0, INT1, INT3, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	–	V
		RESET			0.1	1.2	–	V
IIH	Input "H" current		VI = 5 V, Vcc = 5.0 V		–	–	5.0	μA
IIL	Input "L" current		VI = 0 V, Vcc = 5.0 V		–	–	−5.0	μA
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 5.0 V		25	50	100	kΩ
RfXIN	Feedback resistance	XIN			–	0.3	–	MΩ
RfXCIN	Feedback resistance	XCIN			–	8	–	MΩ
VRAM	RAM hold voltage		During stop mode		1.8	–	–	V

Note:
1.   4.2 V ≤ Vcc ≤ 5.5 V and Topr = −20 to 85°C (N version) / −40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Timing requirements
(Unless Otherwise Specified: VCC = 2.2 V, VSS = 0 V at Topr = 25°C)

Table 5.31   External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t$_{C(XOUT)}$	XOUT input cycle time	200	–	ns
t$_{WH(XOUT)}$	XOUT input "H" width	90	–	ns
t$_{WL(XOUT)}$	XOUT input "L" width	90	–	ns
t$_{C(XCIN)}$	XCIN input cycle time	14	–	μs
t$_{WH(XCIN)}$	XCIN input "H" width	7	–	μs
t$_{WL(XCIN)}$	XCIN input "L" width	7	–	μs
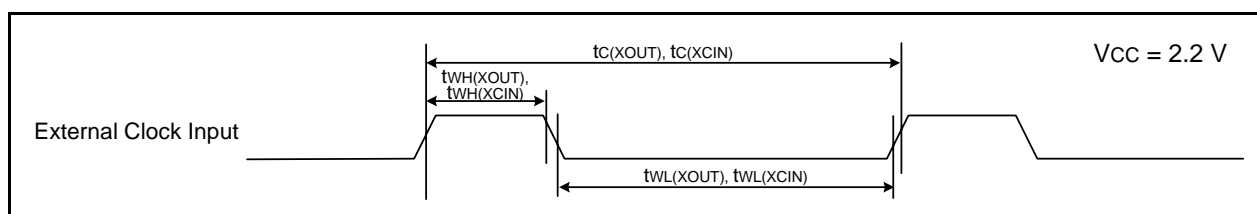
Figure 5.16   External Clock Input Timing Diagram when VCC = 2.2 V

Table 5.32   TRAIO Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t$_{C(TRAIO)}$	TRAIO input cycle time	500	–	ns
t$_{WH(TRAIO)}$	TRAIO input "H" width	200	–	ns
t$_{WL(TRAIO)}$	TRAIO input "L" width	200	–	ns
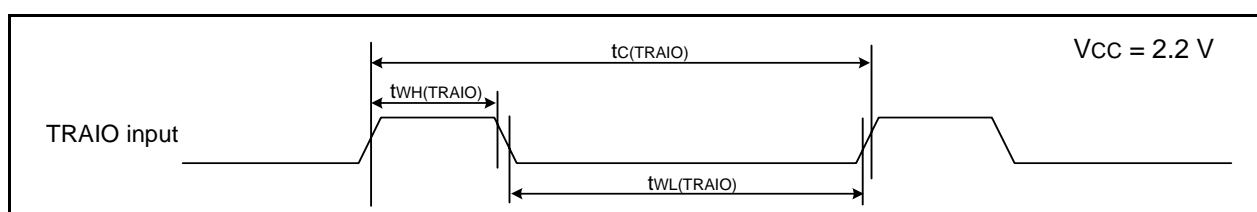
Figure 5.17   TRAIO Input Timing Diagram when VCC = 2.2 V

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.